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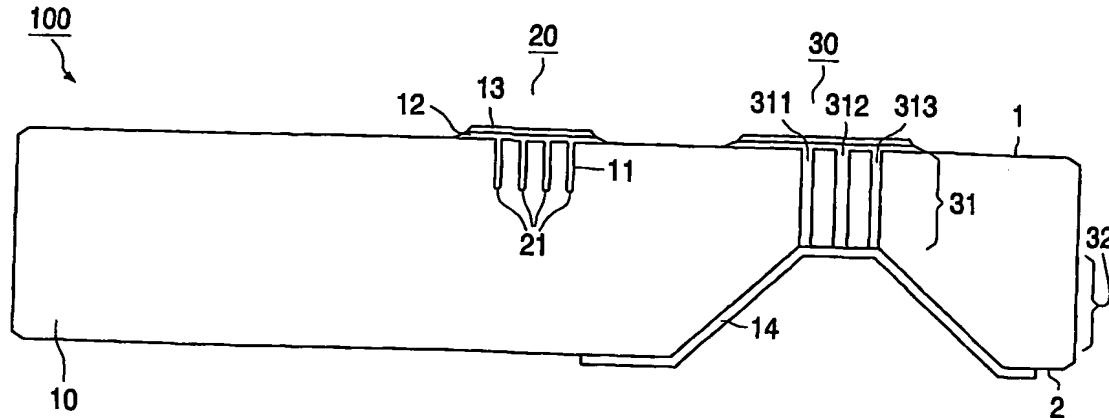
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[Continued on next page]

(54) Title: ELECTRONIC DEVICE, ASSEMBLY AND METHODS OF MANUFACTURING AN ELECTRONIC DEVICE



(57) Abstract: A semiconductor substrate comprises both vertical interconnects and vertical capacitors with a common dielectric layer. The substrate can be suitably combined with further devices to form an assembly. The substrate can be made in etching treatments including a first step on the one side, and then a second step on the other side of the substrate.



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